

L Number	Hits	Search Text	DB	Time stamp
1	294285	heat with (spreader sink stiffener stiffening metal radiate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:19
2	39924	(heat with (spreader sink stiffener stiffening metal radiate)) with (board pcb cb pb substrate carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:22
3	4	((heat with (spreader sink stiffener stiffening metal radiate)) with (board pcb cb pb substrate carrier)) with (coreless thincore (thin adj core))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:21
4	53184	(heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:21
5	5	((heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)) same (coreless thincore (thin adj core))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:22
6	17016	((heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)) same (semiconductor ic chip die (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:23
7	6360	((heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)) same (semiconductor ic chip die (integrated adj circuit))) same (mounting mountable mount mounted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:24
8	3045	((heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)) same (semiconductor ic chip die (integrated adj circuit))) same (mounting mountable mount mounted)) and (extend extended extending tranverse extension)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:25
9	2141	((heat with (spreader sink stiffener stiffening metal radiate)) same (board pcb cb pb substrate carrier)) same (semiconductor ic chip die (integrated adj circuit))) same (mounting mountable mount mounted)) and (extend extended extending tranverse extension)) and (package packaged packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/19 08:26